TecNews

VEROTEC Electronics Packaging

Issue 24

Welcome: This is the 24th edition of TecNews the Newsletter from Verotec. In this edition, latest news announces another new appointment at Verotec. Verotec's attendance at the Southern Manufacturing & Electronics show and a new seat of Solid works. We feature our Slimline wall box and discuss a cPCI system in recent projects

Headlines

- **Welcome / Latest News**
- **Product Feature: Slimline Wallbox**
- **Recent Projects: CompactPCI Systems**

BSI REGISTERED FIRM

UKAS QUALITY MANAGEMENT 003

BS ISO 9001:2008   Reg: FM 569208

Latest News:

New Appointments at Verotec:

Verotec is pleased to announce the appointment of **Andrew Brickell** to the post of Design & Engineering Manager. Andrew joins Verotec from Eschmann, the medical equipment manufacturer. Previously he worked for BICC Vero and Elma where he designed enclosures and integrated systems. Andrew will be working closely with Verotec's marketing and operations teams to help develop new standard products and design special products for specific customer applications. As well as using Pro-Engineer3D modelling. Andrew is also proficient in Solidworks, which is fast becoming the industry standard 3D modelling software.

Exhibitions:

In February Verotec attended the Southern Manufacturing and Electronics Show, in Farnborough. The show took place on the

13th and 14th of February and is becoming the most significant events in the electronics industry. Tim Armstrong, Verotec's Commercial Director, said, "the show was very well attended and we were pleased to come away with a number of good enquiries". Verotec used the exhibition to launch its new Verotec Instrument case range and TecServ+, the new customisation service which the company is now operating.

3D CAD Software:

In order to meet the latest demands of its customers Verotec has installed a seat of Solidworks 3D CAD software. In addition to the Pro-Engineer already used by the company the latest version of Solidworks provides Verotec with a highly flexible design resource. By being able create "native" design files Verotec will be able to transfer data and file "history" between its systems and 3D CAD systems of its customers.

If you would like to know more then please contact Verotec's sales team on 02380 246900 or e-mail: sales@verotec.co.uk

Product Feature: Slimline Wallbox

Verotec's Slimline Wallbox is a low profile 2.5U x 19" enclosure suited to telecom/data networking applications. The equipment is mounted vertically overcoming space restrictions and as well as usual routers or hubs there is room to fit a cable splice and tails providing maximum flexibility for the enclosure. The back of the Slimline Wallbox is pre-drilled for easy wall mounting and the door is fitted with a keyed lock, preventing casual entry into the enclosure.

The key features of Verotec's Slimline Wallbox are:

- A low profile for fitting to exposed positions
- Key locking
- Wall mounting slots in the Rear Panel
- Multiple glanding facilities
- Colour matching, RAL 7035 light grey and RAL 7037 dust grey, to other Verotec product ranges
- Supplied with drilling template for wall mounting

Recent Projects: CompactPCI Systems

Verotec's KM6-RF subrack system was designed to address the requirements of IEEE 1101.10/11, which builds on the IEC 60297-3 standard to offer a number of improvements. These include better EMC, ESD protection, front panel coding, a rear transition area and also the use of injector/ejector style handles to aid the insertion and extraction of boards with high-density connectors. This packaging standard is adopted by a number of industrial computing platforms including VME64x, OpenVPX and CompactPCI. The latter provides a robust PCI based formfactor, used in a number of market applications included telecoms and industrial control. Verotec have recently designed, manufactured and delivered two examples of such; a 3U/84HP and 3U/42HP system, both with DC input panels, 32Bit CompactPCI backplanes and 300W power supplies.

Issue 24